

May 2000 Revised May 2000

74LVTH16835 Low Voltage 18-Bit Universal Bus Driver with 3-STATE Outputs (Preliminary)

General Description

The LVTH16835 consists of 18-bit universal bus drivers which combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, or clocked modes. Data flow from A to Y is controlled by the output-enable $\overline{(OE)}$ input. This device operates in the transparent mode when the latch-enable (LE) input is HIGH. The A data is latched if the clock (CLK) input is held at a HIGH or LOW logic level. If LE is LOW, the A-bus data is stored in the latch/flip-flop on the LOW-to-HIGH transition of the CLK. When \overline{OE} is HIGH, the outputs are in the high-impedance state.

The LVTH16835 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs

The bus driver is designed for low voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVTH16835 is fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining low power dissipation

Features

- \blacksquare Input and output interface capability to systems at 5V V_{CC}
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -32 mA/+64 mA
- Latch-up performance exceeds 500 mA

Ordering Code:

Order Number	Package Number	Package Description
74LVTH16835MEA	MS56A	56-Lead Shrink Small Outline Package (SSOP), JEDEC MO-118, 0.300 Wide
74LVTH16835MTD	MTD56	56-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

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DS500102

Connection Diagram



Pin Descriptions

Pin Names	Description
A ₁ -A ₁₈	Data Register Inputs
A ₁ -A ₁₈ Y ₁ -Y ₁₈	3-STATE Outputs
CLK	Clock Pulse Input
ŌĒ	Output Enable Input
LE	Latch Enable Input

Truth Table

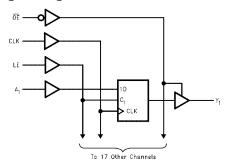
	Inp	Output		
OE	LE	CLK	Α	Y
Н	Χ	Х	Χ	Z
L	Н	Χ	L	L
L	Н	X	Н	Н
L	L	\uparrow	L	L
L	L	\uparrow	Н	Н
L	L	Н	Χ	Y ₀ (Note 1)
L	L	L	Χ	Y ₀ (Note 2)

H = HIGH Voltage Level
X = Immaterial
↑ = HIGH-to-LOW Clock Transition L = LOW Voltage Level

Note 1: Output level before the indicated steady-state input conditions were established, provided that CLK was HIGH before LE went LOW.

Note 2: Output level before the indicated steady-state input conditions were established.

Logic Diagram



Preliminary

Symbol	Parameter	Value	Conditions	Units
V _{CC}	Supply Voltage	-0.5 to +4.6		V
VI	DC Input Voltage	-0.5 to +7.0		V
Vo	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		-0.5 to +7.0	Output in HIGH or LOW State (Note 4)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
l _{ok}	DC Output Diode Current	-50	V _O < GND	mA
l _o	DC Output Current	64	V _O > V _{CC} Output at HIGH State	mA
		128	V _O > V _{CC} Output at LOW State	IIIA
I _{cc}	DC Supply Current per Supply Pin	±64		mA
I _{GND}	DC Ground Current per Ground Pin	±128		mA
T _{STG}	Storage Temperature	-65 to +150		°C

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage	2.7	3.6	V
VI	Input Voltage	0	5.5	V
Гон	HIGH-Level Output Current		-32	mA
I _{OL}	LOW-Level Output Current		64	mA
T _A	Free-Air Operating Temperature	-40	85	°C
Δt/ΔV	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V	0	10	ns/V

Note 3: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 4: I_O Absolute Maximum Rating must be observed.

DC Electrical Characteristics

Symbol	Parameter		V _{CC}	T _A = -40°C	C to +85°C	Units	Conditions
Symbol			(V)	Min	Max	Units	Conditions
V _{IK}	Input Clamp Diode Voltage		2.7		-1.2	V	I _I = -18 mA
V _{IH}	Input HIGH Voltage		2.7-3.6	2.0		V	V _O ≤ 0.1V or
V _{IL}	Input LOW Voltage		2.7-3.6		0.8	V	$V_O \ge V_{CC} - 0.1V$
V _{OH}	Output HIGH Voltage		2.7-3.6	V _{CC} - 0.2		V	$I_{OH} = -100 \mu A$
		Ī	2.7	2.4		V	$I_{OH} = -8 \text{ mA}$
		Ī	3.0	2.0		V	I _{OH} = -32 mA
V _{OL}	Output LOW Voltage		2.7		0.2	V	I _{OL} = 100 μA
		Ī	2.7		0.5	V	I _{OL} = 24 mA
		Ī	3.0		0.4	V	I _{OL} = 16 mA
		Ī	3.0		0.5	V	I _{OL} = 32 mA
		Ī	3.0		0.55	V	I _{OL} = 64 mA
I _{I(HOLD)}	Bushold Input Minimum Drive		3.0	75		μΑ	V _I = 0.8V
				-75		μΑ	V _I = 2.0V
I _{I(OD)}	Bushold Input Over-Drive		3.0	500		μΑ	(Note 5)
	Current to Change State			-500		μΑ	(Note 6)
I _I	Input Current		3.6		10	μΑ	V _I = 5.5V
		Control Pins	3.6		±1	μΑ	V _I = 0V or V _{CC}
		Data Pins	3.6		-5	μΑ	$V_I = 0V$
					1	μΑ	$V_I = V_{CC}$
I _{OFF}	Power Off Leakage Current		0		±100	μΑ	$0V \le V_I \text{ or } V_O \le 5.5V$
I _{PU/PD}	Power up/down 3-STATE		0-1.5V		±100	μА	V _O = 0.5V to 3.0V
	Output Current		0-1.5 V		±100	μΑ	$V_I = GND \text{ or } V_{CC}$
I _{OZL}	3-STATE Output Leakage Cu	irrent	3.6		- 5	μΑ	$V_0 = 0.5V$
I _{OZH}	3-STATE Output Leakage Cu	irrent	3.6		5	μΑ	V _O = 3.0V
I _{OZH} +	3-STATE Output Leakage Cu	irrent	3.6		10	μΑ	$V_{CC} < V_O \le 5.5V$
I _{CCH}	Power Supply Current		3.6		0.19	mA	Outputs HIGH
I _{CCL}	Power Supply Current		3.6		5	mA	Outputs LOW
I _{CCZ}	Power Supply Current		3.6		0.19	mA	Outputs Disabled
I _{CCZ} +	Power Supply Current	ĺ	3.6		0.19	mA	$V_{CC} \le V_O \le 5.5V$,
							Outputs Disabled
ΔI_{CC}	Increase in Power Supply Cu	irrent	3.6		0.2	mA	One Input at V _{CC} – 0.6V
	(Note 7)						Other Inputs at V _{CC} or GNE

Note 5: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Dynamic Switching Characteristics (Note 8)

Symbol	Parameter	v _{cc}	T _A = 25°C		Units	Conditions	
Symbol	Falametei	(V)	Min	Тур	Max	Units	$\mbox{C}_{\mbox{\scriptsize L}}=\mbox{50}\mbox{ pF, R}_{\mbox{\scriptsize L}}=\mbox{500}\Omega$
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3		0.8		V	(Note 9)
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3		-0.8		V	(Note 9)

Note 8: Characterized in SSOP package. Guaranteed parameter, but not tested.

Note 9: Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

Note 6: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

 $[\]textbf{Note 7:} \ This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.$

AC Electrical Characteristics

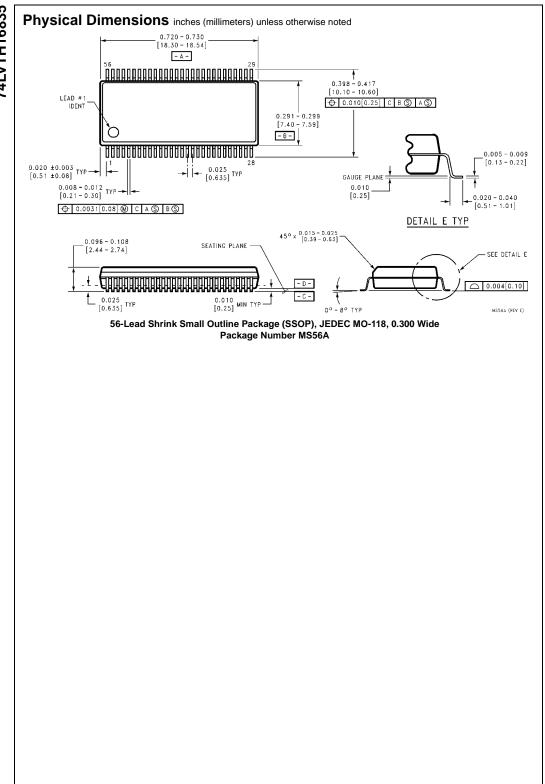
			T _A = -40°	C to +85°C,	C _L = 50 pF,	$R_L = 500 \Omega$	
Symbol	Par	V _{CC} = 3	.3 ± 0.3V	V _{CC}	Units		
		Min	Max	Min	Max		
f _{MAX}		150		150		MHz	
t _{PLH}	Propagation Delay	1.3	3.7	1.3	4.0		
t _{PHL}	A to Y		1.3	3.7	1.3	4.0	ns
t _{PLH}	Propagation Delay	1.5	5.1	1.5	5.7	ns	
t _{PHL}	LE to Y	1.5	5.1	1.5	5.7	115	
t _{PLH}	Propagation Delay	1.5	5.1	1.5	5.7	ns	
t _{PHL}	CLK to Y	1.5	5.1	1.5	5.7	ns	
t _{PZH}	Output Enable Time	1.3	4.6	1.3	5.5	ns	
t_{PZL}		1.3	4.6	1.3	5.5		
t _{PHZ}	Output Disable Time	1.7	5.8	1.7	6.3		
t _{PLZ}			1.7	5.8	1.7	6.3	ns
t _S	Setup Time	A before CLK	2.1		2.4		
		A before LE, CLK HIGH	2.3		1.5		ns
		A before LE, CLK LOW	1.5		0.5		
t _H	Hold Time	A after CLK	1.0		0.0		ns
		A after LE	0.8		0.8		115
t _W	Pulse Duration	LE HIGH	3.3		3.3		no
		CLK HIGH or LOW	3.3		3.3		ns
toslh	Output to Output Skew	•		1.0		1.0	no
toshl	(Note 10)			1.0		1.0	ns

Note 10: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

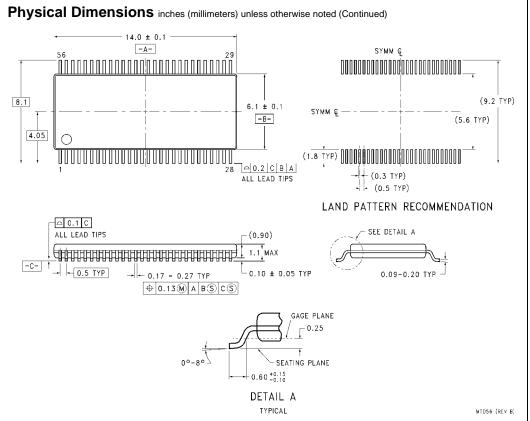
Capacitance (Note 11)

Symbol Parameter		Conditions	Typical	Units	
C _{IN}	Input Capacitance	$V_{CC} = 0V$, $V_I = 0V$ or V_{CC}	4	pF	
C _{OUT}	Output Capacitance	$V_{CC} = 3.0V$, $V_{O} = 0V$ or V_{CC}	8	pF	

Note 11: Capacitance is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.



Preliminary



56-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD56

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